98426–YXX–XX–XXXLF

PLATING
- G : 0.76 GXT
  2µm MIN MATTE TIN ON TAIL
- S : 0.38 GXT
  2µm MIN MATTE TIN ON TAIL
- F : GOLD FLASH /2µm MIN TIN ON TAIL
- T : 2µm MIN FULL TIN
  1.27µm NICKEL MIN UNDERPLATING

LEAD FREE AND RoHS COMPATIBLE, NOTE 6

BODY HEIGHT : XXX
- MIN= 104 (10.4MM)
- MAX= 290 (29.0MM)

PACKAGING, NOTE 3

NO. OF POS PER ROW, 03 TO 25

PIN STYLE	OAL
01	12.8
02	13.5
03	14.1
04	15.6
05	16.3
06	17.1
07	18.3
08	19.1
09	20.3
10	21.1
11	22.3
12	23.3
13	26.0
14	28.0
15	30.0
16	32.0
17	11.0

NOTES:

1 – MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC UL 94V–0, COLOR CREAM (SHROUD) AND BLACK(UNSHROUDED)

2 – MATERIAL TERMINAL: COPPER ALLOY

3 – PACKAGING
- – = STANDARD PACKAGING IN BLIBOX
- S = CUSTOM PACKAGING IN TUBE ONLY FOR PIN STYLE 17

4 – SHROUDED RETENTION FORCE 3N MIN PER POSITION

5 – 0.3 MAX PROTRUSION FOR –03 TO 11

6 – RoHS COMPATIBLE PRODUCT SPECIFICATIONS

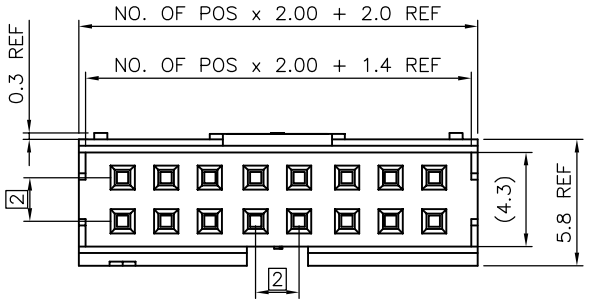
a – PLATING:
- "LF" MEANS THE PRODUCT IS LEAD–FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

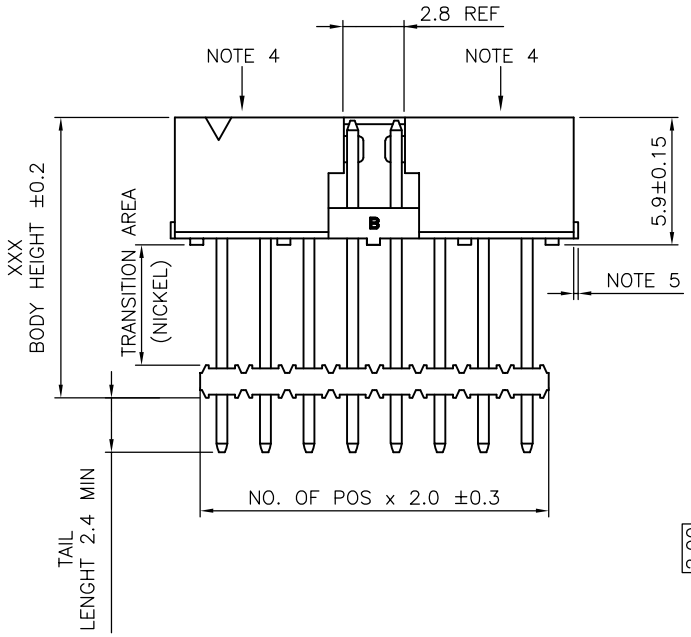
b – MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

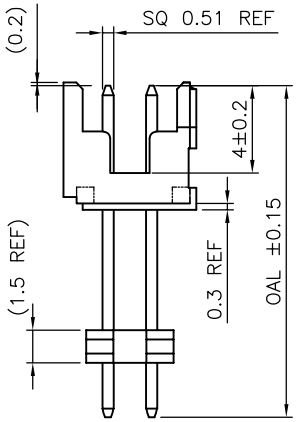
c – LABELING:
- MEETS PACKAGING SPECS AS PER GS–14–920

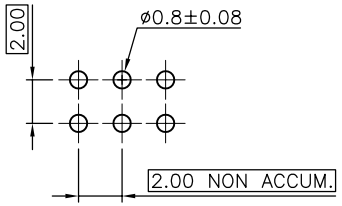
d – LEGAL STATEMENT: SEE GS–47–0004

6 – THIS PRODUCT IS NOT INTENDED TO BE USED THROUGH REFLOW PROCESS









RECOMMENDED HOLE PATTERN

ltr	ecn no	dr	date
A	F09–0227	JCO	09.12.07
B	F10–0067	JCO	10.06.29
C	B–18972	LMU	14.10.01
D	B–19190	LMU	14.10.24
E	B–20291	BVE	15.02.19
F	F–27987	LMU	17.09.18

mat'l. code

surface ISO 1302

tolerance ISO 406 ISO 1101

tolerances unless otherwise specified: angles; linear X.X ±0.3, X.XX ±0.13, X.XXX ±0.05

projection

mm

scale 1:1

dr	L.MULIN	09.04.02
engr	J.COMPAGNON	09.04.02
chr	JCO	09.12.07
appd	J.CO	09.12.07

product family: MINITEK

title: SHR STACKING HEADER MINITEK

dwg no: 98426 — sheet 1 of 1 — size A3

type: CUSTOMER Drawing

sheet index — revision sheet

form: A3

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